To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSK122

Silicon Epitaxial Planar Diode for High Voltage Switching

ADE-208-172D (Z)

Rev.4
Dec. 2000

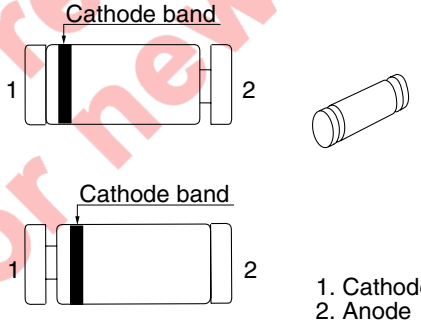
Features

- High reverse voltage. (V_R = 400 V)
- LLD package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Cathode band	Package Code
HSK122	Orange	LLD

Pin Arrangement



1. Cathode
2. Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	410	V
Reverse voltage	V_R	400	V
Peak forward current	I_{FM}	625	mA
Non-Repetitive peak forward surge current	I_{FSM} *1	1	A
Average forward current	I_O	150	mA
Junction temperature	Tj	175	°C
Storage temperature	Tstg	–65 to +175	°C

Note: Within 1s forward surge current.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	1.2	V	I_F = 100 mA
Reverse current	I_R	—	—	1.0	µA	V_R = 400 V
Capacitance	C	—	—	10	pF	V_R = 0 V, f = 1 MHz
Reverse recovery time	t_{rr}	—	—	10	µs	I_F = 30 mA, V_R = 10 V, R_L = 2 kΩ

Main Characteristic

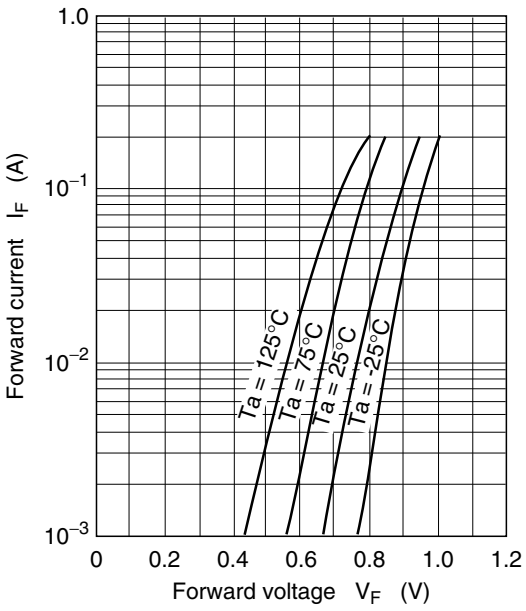


Fig.1 Forward current Vs. Forward voltage

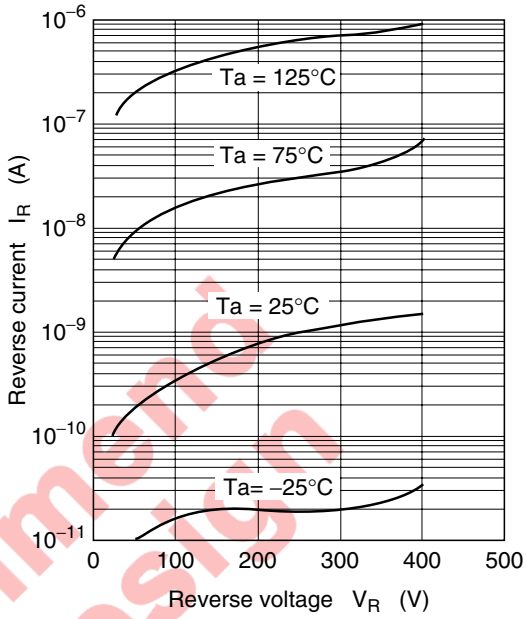


Fig.2 Reverse current Vs. Reverse voltage

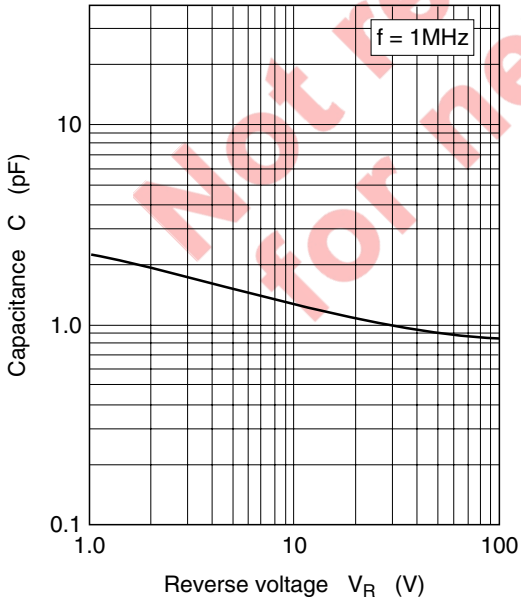
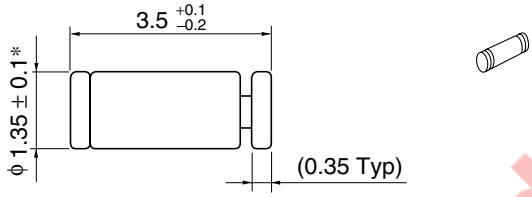


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	LLD
JEDEC	—
EIAJ	—
Mass (reference value)	0.027 g

* HSK122: φ 1.4 ± 0.1 type

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